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# EE566 Solid State Devices

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Dept of Electrical Engineering

University of Notre Dame

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## Assignment 10

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Due: 04/31/2005

### Reading

Chapter 9 of Muller/Kamins/Chan (**MKC**).

### Problem 1 (Electric field along the channel of a MOSFET)

Problem **9.18**, MKC. Comment, after drawing the electric field profile from the source to drain region, why in current short gate-length MOSFETs, a lightly-doped-drain (LDD) halo implant is employed to enhance device performance. You can view the LDD MOSFET process flow at the following website - <http://www.ee.mnsu.edu/~khaliq/archive/ee5480/modules/lightly.html>

### Problem 2 (CMOS improvements with scaling)

Problem **9.16**, MKC. Explain the rationale behind the "constant-field scaling" paradigm.

### Problem 3 (Subthreshold leakage currents)

Subthreshold leakage current flowing between the source and the drain is a major source of static power dissipation in MOSFET digital logic circuits.

a) Show that the subthreshold leakage current varies with the gate voltage as

$$I_{DS} \approx I_0 e^{\frac{\eta q V_{GS}}{kT}}, \text{ where}$$
$$\eta = \frac{1}{1 + 3t_{ox} / x_{depl}}$$

b) Plot the inverse subthreshold slope  $S = \ln 10 \cdot (kT / \eta q)$  for various ITRS technology nodes.

c) Explain why a low  $S$  is ideal for digital applications. What is the minimum  $S$  at room temperature? Explain why as gate lengths get scaled down further,  $S$  will increase unless proper care is taken in the design of the MOSFETs.

d) Recently, there have been some proposals of new device architectures to reduce  $S$  from the minimum values obtainable in traditional MOSFET design. Do some research and comment on these approaches.

### Problem 4 (Short channel effects in MOSFETs)

Explain briefly, using sketches and band diagrams, how short-channel-effect (SCE) changes the device performance as compared to a long-channel MOSFET. You should comment upon such effects as Drain-Induced Barrier Lowering (DIBL), subsurface punchthrough, mobility degradation, carrier velocity in the channel, and the effects on  $V_T$ ,  $I_{Dsat}$ , and the speed  $f_T$  of the MOSFET.

NO more assignments!!!

